

SPECIALTY ABRASIVES FOR CMP

MATERIALS • TECHNOLOGY ROADMAPS •
SUPPLIERS • MARKET FORECASTS

COMPREHENSIVE ANALYSIS OF ADVANCED PARTICLES FOR CMP SLURRIES IN SEMICONDUCTORS

As semiconductor technologies advance, complex architectures such as **GAA transistors (GAA)**, **High Bandwidth Memory (HBM)**, and **3D NAND** are driving demand for Chemical Mechanical Planarization (CMP) to achieve ultra-smooth chip surfaces.

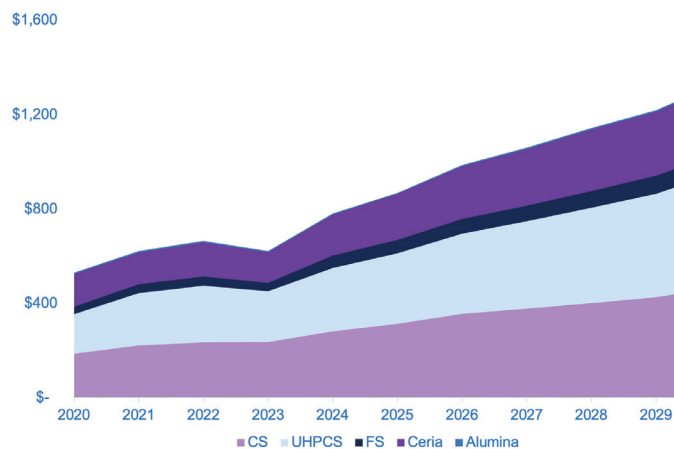
The Specialty Abrasives for CMP report offers a **10-year global outlook, with detailed 5-year forecasts on market trends, key suppliers, and lower-abrasive formulations** designed to improve precision and reduce defects.

Powered by proprietary research and the SEMI-Linx Materials Model, the report offers insights into abrasive trends, process dependencies, and material consumption to support strategic planning and uncover growth opportunities.

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DETAILS



CMP Abrasive Forecast \$M



BENEFITS

- Anticipate Technology Shifts**
Stay ahead of evolving CMP requirements with insights into advanced device architectures and next-generation slurry technologies.
- Support Strategic Decisions**
Leverage actionable market intelligence on abrasive technologies, supplier dynamics & CMP innovations to guide R&D, investment, and strategy.
- Optimize Growth & Mitigate Risks**
Identify the shift toward lower-abrasive, chemically-driven slurries to improve production planning, minimize uncertainty & operational disruption.
- Supplier Benchmarking**
Compare supplier capabilities, competitive positioning, and market dynamics to strengthen sourcing strategies and strategic partnerships.
- Deeper Market Insights**
Access comprehensive CMP materials, process, and technology analysis to identify trends and improve competitive positioning.

METHODOLOGY

SEMI and Linx employ a rigorous research methodology that combines direct engagement with leading CMP users, equipment suppliers, consumable suppliers, and technology providers with the SEMI-Linx Materials Model. This approach enables the identification of key technology trends, supplier activities, and market dynamics, delivering reliable forecasts and valuable market insights into the CMP abrasive market.

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REPORT HIGHLIGHTS

- **Emerging Process Analysis**

Examine next-generation CMP processes supporting advanced device architectures, including GAA, HBM, and 3D NAND.

- **Materials & Applications**

Gain insights into slurry chemistries, material selectivity, purity, defectivity, and key CMP applications, including:

- Copper Bulk
- Barrier
- Tungsten
- Cobalt
- Ruthenium
- Molybdenum
- Oxide and Polysilicon
- STI and Ceria-based
- Emerging Applications
- Silicon Wafer Polishing

- **Abrasive Trends**

Explore the 3 primary drivers shaping abrasive demand: slurry market growth, semiconductor technology roadmaps, and wafer market projections.

- **Demand Forecasting**

SEMI-Linx Materials Model and projections of CMP abrasive demand, including key supplier identification.

- **Competitive Intelligence**

Evaluate supplier positioning, competitive dynamics, and emerging business opportunities across the specialty abrasives market.

DETAILS:

- **Publication Schedule:** Biennial
- **Format:** Microsoft® Excel® file (.xls), PowerPoint® file
- **Principal Analysts:** SEMI and Linx Consulting

RELATED REPORTS:

- **CMP Technologies & Markets**
- **Wafer Fab Materials Quarterly**
- **Advanced Cleaning & Surface Preparation**
- **Materials Market Data Subscription (MMDS)**



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